

# DFR1A THRU DFR1M

## 1.0A Surface Mount Fast Recovery Rectifiers-50-1000V

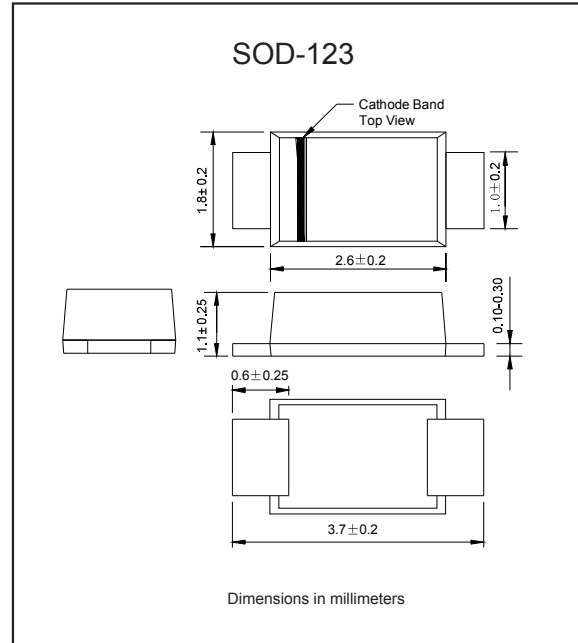
### Features

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:  
250°C/10 seconds, 0.375"(9.5mm) lead length,  
5 lbs. (2.3kg) tension
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case**: JEDEC SOD-123 molded plastic body over passivated chip
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any
- ◆ **Weight**: 0.0007 ounce, 0.02 grams

### Package outline



### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I <sub>O</sub>			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I <sub>FSM</sub>			25	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 25°C	I <sub>R</sub>			5.0	μA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 100°C				50	
Thermal resistance	Junction to ambient NOTE 1	R <sub>θJA</sub>		50		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		15		pF
Storage temperature		T <sub>STG</sub>	-65		+150	°C

SYMBOLS	V <sub>RM</sub> <sup>*1</sup> (V)	V <sub>RMS</sub> <sup>*2</sup> (V)	V <sub>R</sub> <sup>*3</sup> (V)	V <sub>F</sub> <sup>*4</sup> (V)	t <sub>rr</sub> <sup>*5</sup> (ns)	Operating temperature T <sub>Jr</sub> (°C)
DFR1A	50	35	50	1.30	150	-55 to +150
DFR1B	100	70	100			
DFR1D	200	140	200			
DFR1G	400	280	400		250	
DFR1J	600	420	600			
DFR1K	800	560	800		500	
DFR1M	1000	700	1000			

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@I<sub>F</sub>=1.0A
- \*5 Maximum Reverse recovery time, note 2

**Note:** 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas  
2. Reverse recovery time test condition, I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

DFR1A THRU DFR1M

Rating and characteristic curves (DFR1A THRU DFR1M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

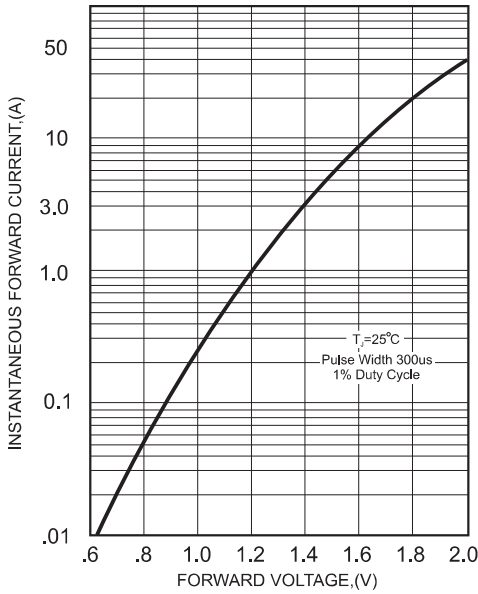


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

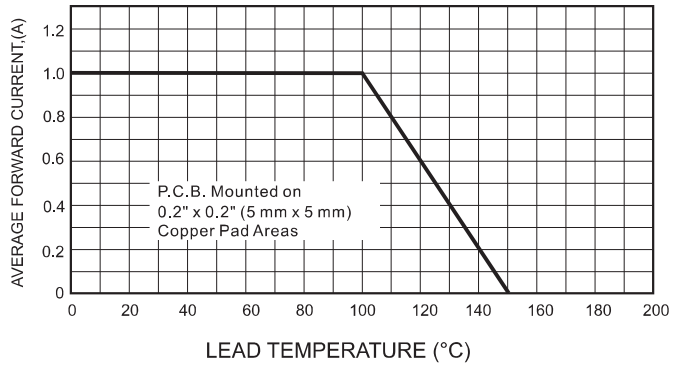
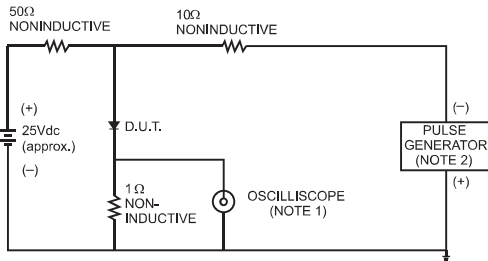


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

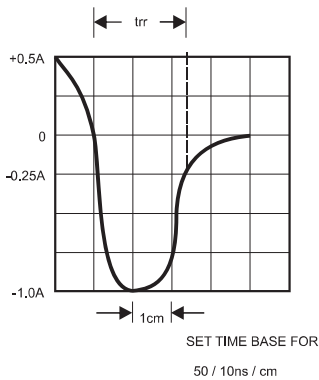


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

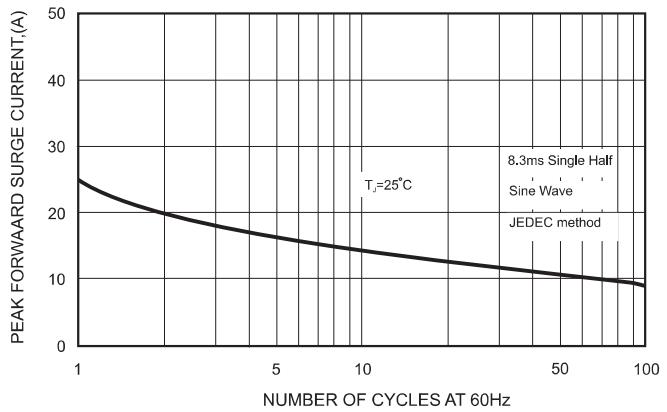
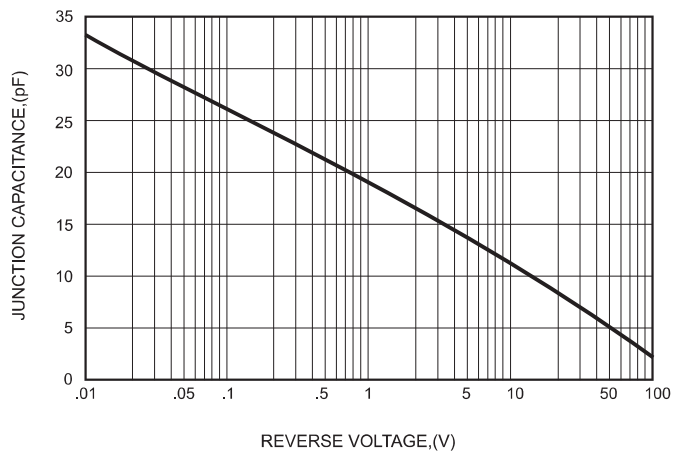
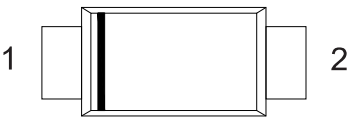



FIG.5-TYPICAL JUNCTION CAPACITANCE



# DFR1A THRU DFR1M

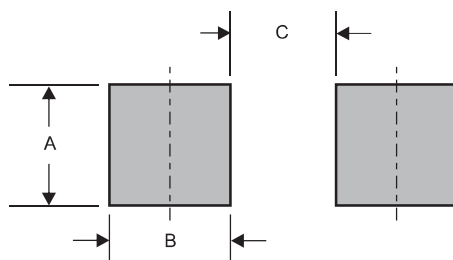
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
DFR1A	F 1
DFR1B	F 2
DFR1D	F 3
DFR1G	F 4
DFR1J	F 5
DFR1K	F 6
DFR1M	F 7

## Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)